

| L Number | Hits | Search Text   | DB  | Time stamp          |
|----------|------|---|---|---------------------|
| 22       | 3    | 257/667,787.ccls. and dummy adj pads and (chip die IC)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>17:40 |
| 23       | 2    | 257/667,787.ccls. and dummy adj pads and pitch  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>17:42 |
| 24       | 0    | 257/670,669,674.ccls. and dummy adj pads and pitch  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>17:42 |
| 25       | 5    | 257/668.ccls. and dummy adj pads and pitch  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>17:44 |
| 26       | 49   | dummy adj pads and pitch  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>17:50 |
| 27       | 161  | dummy adj pads and (IC die chip)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:04 |
| 28       | 2    | ("6268644").PN.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:07 |
| 29       | 0    | yuan-po-hao.in.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:07 |
| 30       | 38   | wu-chi-chuan.in.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:10 |
| 31       | 1    | chen-chih-shun.in.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:13 |
| 32       | 2680 | (IC chip die) and dum\$4 and pitch  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:22 |
| 33       | 2    | ("6297078").PN.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:23 |
| 34       | 11   | ("4928162"   "5045919"   "5296743"   "5457340"   "5508556"   "5563446"   "5565709"   "5596227"   "5684332"   "5780772"   "5843808").PN. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:22 |
| 35       | 2    | ("5825081").PN.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:28 |

|    |    |   |   |                     |
|----|----|---|---|---------------------|
| 36 | 12 | 257/671,674.ccls. and dum\$4 and (IC die chip)            | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:30 |
| 37 | 25 | 438/123-124.ccls. and dum\$4 and (IC die chip) and pit\$5 | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:34 |
| 38 | 0  | 438/6134.ccls. and dum\$4 and (IC die chip) and pit\$5    | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:34 |
| 39 | 14 | 438/613.ccls. and dum\$4 and (IC die chip) and pit\$5     | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/20<br>18:34 |